

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	112	((integrated adj circuit) or "IC") and ((non adj float\$4) or (non-float\$4)) and logic	USPAT	OR	OFF	2005/04/07 15:03
L2	159	((integrated adj circuit) or "IC") and ((non adj float\$4) or (non-float\$4)) and logic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 15:03
L3	52	2 and (terminal and (solder or ball or pad))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 15:04
L4	9	3 and (capacitor and (insulat\$4 or dielectric))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 15:17
L5	4	"6686659"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 15:17
L6	7	("4273859" "5808853" "6094090" "6175345" "6222246" "6243311" "6335568").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/07 15:21
L9	12	("3021589" "3278815" "3292240" "3303393" "3638085" "3897074" "4071878" "4104697").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/04/07 15:26
L10	20	("4439813").URPN.	USPAT	OR	OFF	2005/04/07 15:25
L11	32	3 not (4 5 6 7 9 10)	USPAT	OR	OFF	2005/04/07 15:28
L12	2	11 and decoupl\$4	USPAT	OR	OFF	2005/04/07 15:27
S1	290	substrate and ((bump or solder or (solder adj ball) or protrusion or protrusion or ball) near2 capacitor) and (dielectric or insulat\$4)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/28 16:10
S2	59	seshan-krishna.in.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/25 17:23
S3	24	("4141022" "5605861" "5770490" "5882965" "5937289" "5965462" "5966632" "5998269" "5998271" "6004837" "6028339" "6087225" "6146962" "6153476" "6190979" "6200834" "6235574" "6258659" "6261894" "6261924" "6261933" "6326657" "6531750" "6548871").PN.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/25 17:23
S4	3	seshan-krishna.in. and ("IC" or (integrated adj circuit)) and node and float\$4 and coupl\$4	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/25 17:23
S5	1	(US-20040108596-\$).did.	US-PGPUB	OR	OFF	2004/10/25 17:23
S6	1	US-20040108596-A1.DID. and (float\$4 or (non-float\$4))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/25 17:23
S7	24	((("4141022" "5605861" "5770490" "5882965" "5937289" "5965462" "5966632" "5998269" "5998271" "6004837" "6028339" "6087225" "6146962" "6153476" "6190979" "6200834" "6235574" "6258659" "6261894" "6261924" "6261933" "6326657" "6531750" "6548871").PN.) not seshan-krishna.in.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/25 17:23
S8	7	("4273859" "5808853" "6094090" "6175345" "6222246" "6243311" "6335568").PN.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/25 17:23
S9	13	("3638083" "4967950" "5075965" "5130779" "5238176" "5251806" "5290732" "5391514" "5451274" "5470787" "5478420" "5597469" "5634268").PN.	USPAT	OR	ON	2004/10/25 17:23

S10	287	(substrate and ((bump or solder or (solder adj ball) or protrusion or protrusion or ball) near2 capacitor) and (dielectric or insulat\$4)) not (seshan-krishna.in. (("4141022" "5605861" "5770490" "5882965" "5937289" "5965462" "5966632" "5998269" "5998271" "6004837" "6028339" "6087225" "6146962" "6153476" "6190979" "6200834" "6235574" "6258659" "6261894" "6261924" "6261933" "6326657" "6531750" "6548871").PN.))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/25 17:23
S12	35	((substrate and ((bump or solder or (solder adj ball) or protrusion or protrusion or ball) near2 capacitor) and (dielectric or insulat\$4)) not (seshan-krishna.in. (("4141022" "5605861" "5770490" "5882965" "5937289" "5965462" "5966632" "5998269" "5998271" "6004837" "6028339" "6087225" "6146962" "6153476" "6190979" "6200834" "6235574" "6258659" "6261894" "6261924" "6261933" "6326657" "6531750" "6548871").PN.))) and (float\$4)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/25 17:24
S13	31	((substrate and ((bump or solder or (solder adj ball) or protrusion or protrusion or ball) near2 capacitor) and (dielectric or insulat\$4)) not (seshan-krishna.in. (("4141022" "5605861" "5770490" "5882965" "5937289" "5965462" "5966632" "5998269" "5998271" "6004837" "6028339" "6087225" "6146962" "6153476" "6190979" "6200834" "6235574" "6258659" "6261894" "6261924" "6261933" "6326657" "6531750" "6548871").PN.))) and (float\$4)) and (die or chip or "IC" or (integrated adj circuit))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/25 17:31
S14	4	((substrate and ((bump or solder or (solder adj ball) or protrusion or protrusion or ball) near2 capacitor) and (dielectric or insulat\$4)) not (seshan-krishna.in. (("4141022" "5605861" "5770490" "5882965" "5937289" "5965462" "5966632" "5998269" "5998271" "6004837" "6028339" "6087225" "6146962" "6153476" "6190979" "6200834" "6235574" "6258659" "6261894" "6261924" "6261933" "6326657" "6531750" "6548871").PN.))) and (float\$4)) not (((substrate and ((bump or solder or (solder adj ball) or protrusion or protrusion or ball) near2 capacitor) and (dielectric or insulat\$4)) not (seshan-krishna.in. (("4141022" "5605861" "5770490" "5882965" "5937289" "5965462" "5966632" "5998269" "5998271" "6004837" "6028339" "6087225" "6146962" "6153476" "6190979" "6200834" "6235574" "6258659" "6261894" "6261924" "6261933" "6326657" "6531750" "6548871").PN.))) and (float\$4)) and (die or chip or "IC" or (integrated adj circuit)))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/25 17:32
S15	252	((substrate and ((bump or solder or (solder adj ball) or protrusion or protrusion or ball) near2 capacitor) and (dielectric or insulat\$4)) not (seshan-krishna.in. (("4141022" "5605861" "5770490" "5882965" "5937289" "5965462" "5966632" "5998269" "5998271" "6004837" "6028339" "6087225" "6146962" "6153476" "6190979" "6200834" "6235574" "6258659" "6261894" "6261924" "6261933" "6326657" "6531750" "6548871").PN.))) not (((substrate and ((bump or solder or (solder adj ball) or protrusion or protrusion or ball) near2 capacitor) and (dielectric or insulat\$4)) not (seshan-krishna.in. (("4141022" "5605861" "5770490" "5882965" "5937289" "5965462" "5966632" "5998269" "5998271" "6004837" "6028339" "6087225" "6146962" "6153476" "6190979" "6200834" "6235574" "6258659" "6261894" "6261924" "6261933" "6326657" "6531750" "6548871").PN.))) and (float\$4))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/25 17:32
S19	182	((substrate and ((bump or solder or (solder adj ball) or protrusion or protrusion or ball) near2 capacitor) and (dielectric or insulat\$4)) not (seshan-krishna.in. (("4141022" "5605861" "5770490" "5882965" "5937289" "5965462" "5966632" "5998269" "5998271" "6004837" "6028339" "6087225" "6146962" "6153476" "6190979" "6200834" "6235574" "6258659" "6261894" "6261924" "6261933" "6326657" "6531750" "6548871").PN.))) not (((substrate and ((bump or solder or (solder adj ball) or protrusion or protrusion or ball) near2 capacitor) and (dielectric or insulat\$4)) not (seshan-krishna.in. (("4141022" "5605861" "5770490" "5882965" "5937289" "5965462" "5966632" "5998269" "5998271" "6004837" "6028339" "6087225" "6146962" "6153476" "6190979" "6200834" "6235574" "6258659" "6261894" "6261924" "6261933" "6326657" "6531750" "6548871").PN.))) and (float\$4))) and capacitor.ab	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/25 17:34

S20	164	(((((substrate and ((bump or solder or (solder adj ball) or protrution or protrusion or ball) near2 capacitor) and (dielectric or insulat\$4)) not (seshan-krishna.in. ("4141022" "5605861" "5770490" "5882965" "5937289" "5965462" "5966632" "5998269" "5998271" "6004837" "6028339" "6087225" "6146962" "6153476" "6190979" "6200834" "6235574" "6258659" "6261894" "6261924" "6261933" "6326657" "6531750" "6548871").PN.))) not (((substrate and ((bump or solder or (solder adj ball) or protrution or protrusion or ball) near2 capacitor) and (dielectric or insulat\$4)) not (seshan-krishna.in. ("4141022" "5605861" "5770490" "5882965" "5937289" "5965462" "5966632" "5998269" "5998271" "6004837" "6028339" "6087225" "6146962" "6153476" "6190979" "6200834" "6235574" "6258659" "6261894" "6261924" "6261933" "6326657" "6531750" "6548871").PN.))) and (float\$4))) and capacitor.ab.) and capacitor.clm.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/25 17:34
S21	117	(((((substrate and ((bump or solder or (solder adj ball) or protrution or protrusion or ball) near2 capacitor) and (dielectric or insulat\$4)) not (seshan-krishna.in. ("4141022" "5605861" "5770490" "5882965" "5937289" "5965462" "5966632" "5998269" "5998271" "6004837" "6028339" "6087225" "6146962" "6153476" "6190979" "6200834" "6235574" "6258659" "6261894" "6261924" "6261933" "6326657" "6531750" "6548871").PN.))) not (((substrate and ((bump or solder or (solder adj ball) or protrution or protrusion or ball) near2 capacitor) and (dielectric or insulat\$4)) not (seshan-krishna.in. ("4141022" "5605861" "5770490" "5882965" "5937289" "5965462" "5966632" "5998269" "5998271" "6004837" "6028339" "6087225" "6146962" "6153476" "6190979" "6200834" "6235574" "6258659" "6261894" "6261924" "6261933" "6326657" "6531750" "6548871").PN.))) and (float\$4))) and capacitor.ab.) and capacitor.clm.) and (bump or ball or solder or terminal or pad).clm.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/25 17:35
S22	83	(((((substrate and ((bump or solder or (solder adj ball) or protrution or protrusion or ball) near2 capacitor) and (dielectric or insulat\$4)) not (seshan-krishna.in. ("4141022" "5605861" "5770490" "5882965" "5937289" "5965462" "5966632" "5998269" "5998271" "6004837" "6028339" "6087225" "6146962" "6153476" "6190979" "6200834" "6235574" "6258659" "6261894" "6261924" "6261933" "6326657" "6531750" "6548871").PN.))) not (((substrate and ((bump or solder or (solder adj ball) or protrution or protrusion or ball) near2 capacitor) and (dielectric or insulat\$4)) not (seshan-krishna.in. ("4141022" "5605861" "5770490" "5882965" "5937289" "5965462" "5966632" "5998269" "5998271" "6004837" "6028339" "6087225" "6146962" "6153476" "6190979" "6200834" "6235574" "6258659" "6261894" "6261924" "6261933" "6326657" "6531750" "6548871").PN.))) and (float\$4))) and capacitor.ab.) and capacitor.clm.) and (bump or ball or solder or terminal or pad).clm.) and (bump or ball or solder or terminal or pad).ab.	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/26 10:18
S23	2	"6466430".URPN.	USPAT	OR	ON	2004/10/25 18:34
S24	19	("3280378" "3346774" "3492536" "4300115" "4332341" "4626804" "4654628" "4658234" "4945399" "5216404" "5379190" "5539186" "5557502" "5621619" "5661450" "5760662" "5923077" "5977863" "6005777").PN.	USPAT	OR	ON	2004/10/25 18:47
S25	8	("3021589" "3278815" "3292240" "3303393" "3638085" "3897074" "4071878" "4104697").PN.	USPAT	OR	ON	2004/10/25 19:06
S26	18	"4439813".URPN.	USPAT	OR	ON	2004/10/25 19:06
S27	3	substrate and (bump or ball or solder) and (decoupl\$4 adj capacitor) and (selector adj logic)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/28 16:12
S28	6	substrate and (bump or ball or solder) and (decoupl\$4 adj capacitor) and (select\$4 near3 logic)	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/28 16:12
S30	3	(substrate and (bump or ball or solder) and (decoupl\$4 adj capacitor) and (select\$4 near3 logic)) not (substrate and (bump or ball or solder) and (decoupl\$4 adj capacitor) and (selector adj logic))	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2004/10/28 16:13